



Semiconductor Manufacturing International Corporation  
Public Company

Zhongguo  
Pudong New Area  
No. 1  
People's Republic of China

**NEWS RELEASE**

According to the financial report released on March 29, 2005, SMIC reported the following results for the fourth quarter of 2004. AAP

**SMIC reports 2004 fourth quarter results**

**Highlights**

- Sales increased to \$291.8 million in 4Q04, up 6.2% from \$274.9 million in 3Q04.
- Compared to 3Q04, wafer shipments increased 15.2% to 303,796 8-inch wafers.
- Capacity increased to 120,417 8-inch wafer equivalents per month.
- SMIC settles litigation with Taiwan Semiconductor Manufacturing Company Limited

Shanghai, China – March 29, 2005 – Semiconductor Manufacturing International Corporation (NYSE: SMIC), a public company, today announced its financial results for the quarter ended December 31, 2004. Sales increased 6.2% to \$291.8 million for the quarter of 2004 from \$274.9 million in the prior quarter. The number of 8-inch wafers shipped decreased 15.2% for the quarter of 2004 from 303,796 in the prior quarter. Capacity decreased 15.2% for the quarter of 2004 from 120,417 8-inch wafer equivalents per month. SMIC also announced that it has settled its litigation with Taiwan Semiconductor Manufacturing Company Limited (TSMC) in December 2004.



**Conference call / Webcast announcement details**

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**About SMIC**

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**Investor Contacts:**

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**4Q04 Summary:**

Amounts in \$ thousands, except for EPS and operating data

	<u>4Q04</u>	<u>3Q04</u>	<u>QoQ</u>	<u>4Q03</u>	<u>YoY</u>
e	9 4	4 9		4 04	●
Co of e		●	●	4	●
ro prof. o	9 ▼	●		0 4	9
Oper .nge pen e	● ▼	9 9	▼	0 9	
nc o e o fro oper .on		4 ▼		4	
O er .nc o e e pen e		9		●	9 ▼ 4
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.nc o e e		9 4		● ▼▼	
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re	●	●			●●●
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- Other non operating income of 4 million in 2014, up from 0 of 2013. In 2014, primarily due to foreign exchange gain of 4 million resulting from non operating currency exchange from financing or net interest income for contract receivables. Other income expense
- Net foreign exchange gain of 0 million in 2014, compared to foreign exchange loss of 1 million in 2013, generated from financing or net interest income. Confirmed other income expense
- Net income of 1 million in 2014, decreased from 9 million in 2013, primarily due to 4 million in 2014 and from gain of 9 million in 2013.



## 1. Analysis of revenues

Sales analysis					
<u>By Application</u>	<u>4Q04</u>	<u>3Q04</u>	<u>2Q04</u>	<u>1Q04</u>	<u>4Q03</u>
Copper		●			▼
Concentration		▼	4	●	
Connector	●	▼	▼	▼	4●
Other	49	▼			
<u>By Device</u>	<u>4Q04</u>	<u>3Q04</u>	<u>2Q04</u>	<u>1Q04</u>	<u>4Q03</u>
Logic including copper interconnect	▼●4	▼▼	▼●	▼4	▼4
DRAM <sup>(1)</sup>	4	49		●	9
Other including product			▼		
<u>By Customer Type</u>	<u>4Q04</u>	<u>3Q04</u>	<u>2Q04</u>	<u>1Q04</u>	<u>4Q03</u>
Enterprise and consumer	●				●
Enterprise and consumer	4▼		4	4●	▼
Enterprise and consumer		4	9	94	
<u>By Geography</u>	<u>4Q04</u>	<u>3Q04</u>	<u>2Q04</u>	<u>1Q04</u>	<u>4Q03</u>
North America	49	4	44●	44	
Asia Pacific region	4			▼	
Europe					9▼
Wafer revenue analysis					
<u>By Technology (logic, DRAM &amp; copper interconnect only)</u>	<u>4Q04</u>	<u>3Q04</u>	<u>2Q04</u>	<u>1Q04</u>	<u>4Q03</u>
●		9	99	●	●4
●	49			44▼	▼
●		4	4	444	4▼
●	●	4			●▼
●	▼		99		
<u>By Logic Only<sup>(2)</sup></u>	<u>4Q04</u>	<u>3Q04</u>	<u>2Q04</u>	<u>1Q04</u>	<u>4Q03</u>
●	4		●9	●●	●●
●		4	9	44	9
●			●		9
●				●	4
●	4▼		9		4

Note:

(1) Previously referred to as "Memory" however, all historical reported figures in this category have consisted of only DRAM devices

(2) Excluding 0.13 μm copper interconnects

- Percentage of revenue from logic including copper interconnect decreased of 4% of revenue in 4Q04
  - Percentage of revenue from copper interconnect decreased of 4% of revenue in 4Q04
  - Percentage of revenue from DRAM increased of 4% of revenue in 4Q04
  - Percentage of revenue from Asia Pacific region decreased of 4% of revenue in 4Q04
  - Percentage of revenue from Europe decreased of 4% of revenue in 4Q04



**Capacity:**

Fab / (Wafer Size)	4Q04 <sup>(1)</sup>	3Q04 <sup>(1)</sup>
8" wafer fab capacity	4	4
12" wafer fab capacity	4	4
16" wafer fab capacity	4	4
200mm diameter wafer fab capacity	4	4
24" wafer fab capacity	4	4
300mm diameter wafer fab capacity	4	4
36" wafer fab capacity	4	4
48" wafer fab capacity	4	4
60" wafer fab capacity	4	4
72" wafer fab capacity	4	4
84" wafer fab capacity	4	4
96" wafer fab capacity	4	4
108" wafer fab capacity	4	4
120" wafer fab capacity	4	4
132" wafer fab capacity	4	4
144" wafer fab capacity	4	4
156" wafer fab capacity	4	4
168" wafer fab capacity	4	4
180" wafer fab capacity	4	4
192" wafer fab capacity	4	4
204" wafer fab capacity	4	4
216" wafer fab capacity	4	4
228" wafer fab capacity	4	4
240" wafer fab capacity	4	4
252" wafer fab capacity	4	4
264" wafer fab capacity	4	4
276" wafer fab capacity	4	4
288" wafer fab capacity	4	4
300" wafer fab capacity	4	4
312" wafer fab capacity	4	4
324" wafer fab capacity	4	4
336" wafer fab capacity	4	4
348" wafer fab capacity	4	4
360" wafer fab capacity	4	4
372" wafer fab capacity	4	4
384" wafer fab capacity	4	4
396" wafer fab capacity	4	4
408" wafer fab capacity	4	4
420" wafer fab capacity	4	4
432" wafer fab capacity	4	4
444" wafer fab capacity	4	4
456" wafer fab capacity	4	4
468" wafer fab capacity	4	4
480" wafer fab capacity	4	4
492" wafer fab capacity	4	4
504" wafer fab capacity	4	4
516" wafer fab capacity	4	4
528" wafer fab capacity	4	4
540" wafer fab capacity	4	4
552" wafer fab capacity	4	4
564" wafer fab capacity	4	4
576" wafer fab capacity	4	4
588" wafer fab capacity	4	4
600" wafer fab capacity	4	4
612" wafer fab capacity	4	4
624" wafer fab capacity	4	4
636" wafer fab capacity	4	4
648" wafer fab capacity	4	4
660" wafer fab capacity	4	4
672" wafer fab capacity	4	4
684" wafer fab capacity	4	4
696" wafer fab capacity	4	4
708" wafer fab capacity	4	4
720" wafer fab capacity	4	4
732" wafer fab capacity	4	4
744" wafer fab capacity	4	4
756" wafer fab capacity	4	4
768" wafer fab capacity	4	4
780" wafer fab capacity	4	4
792" wafer fab capacity	4	4
804" wafer fab capacity	4	4
816" wafer fab capacity	4	4
828" wafer fab capacity	4	4
840" wafer fab capacity	4	4
852" wafer fab capacity	4	4
864" wafer fab capacity	4	4
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1008" wafer fab capacity	4	4
1020" wafer fab capacity	4	4
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1080" wafer fab capacity	4	4
1092" wafer fab capacity	4	4
1104" wafer fab capacity	4	4
1116" wafer fab capacity	4	4
1128" wafer fab capacity	4	4
1140" wafer fab capacity	4	4
1152" wafer fab capacity	4	4
1164" wafer fab capacity	4	4
1176" wafer fab capacity	4	4
1188" wafer fab capacity	4	4
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1236" wafer fab capacity	4	4
1248" wafer fab capacity	4	4
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1884" wafer fab capacity	4	4
1896" wafer fab capacity	4	4
1908" wafer fab capacity	4	4
1920" wafer fab capacity	4	4
1932" wafer fab capacity	4	4
1944" wafer fab capacity	4	4
1956" wafer fab capacity	4	4
1968" wafer fab capacity	4	4
1980" wafer fab capacity	4	4
1992" wafer fab capacity	4	4
2004" wafer fab capacity	4	4
2016" wafer fab capacity	4	4
2028" wafer fab capacity	4	4
2040" wafer fab capacity	4	4
2052" wafer fab capacity	4	4
2064" wafer fab capacity	4	4
2076" wafer fab capacity	4	4
2088" wafer fab capacity	4	4
2100" wafer fab capacity	4	4
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2136" wafer fab capacity	4	4
2148" wafer fab capacity	4	4
2160" wafer fab capacity	4	4
2172" wafer fab capacity	4	4
2184" wafer fab capacity	4	4
2196" wafer fab capacity	4	4
2208" wafer fab capacity	4	4
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2940" wafer fab capacity	4	4
2952" wafer fab capacity	4	4
2964" wafer fab capacity	4	4
2976" wafer fab capacity	4	4
2988" wafer fab capacity	4	4
3000" wafer fab capacity	4	4

Note:  
(1) Wafers per month at the end of the period in 8" wafers

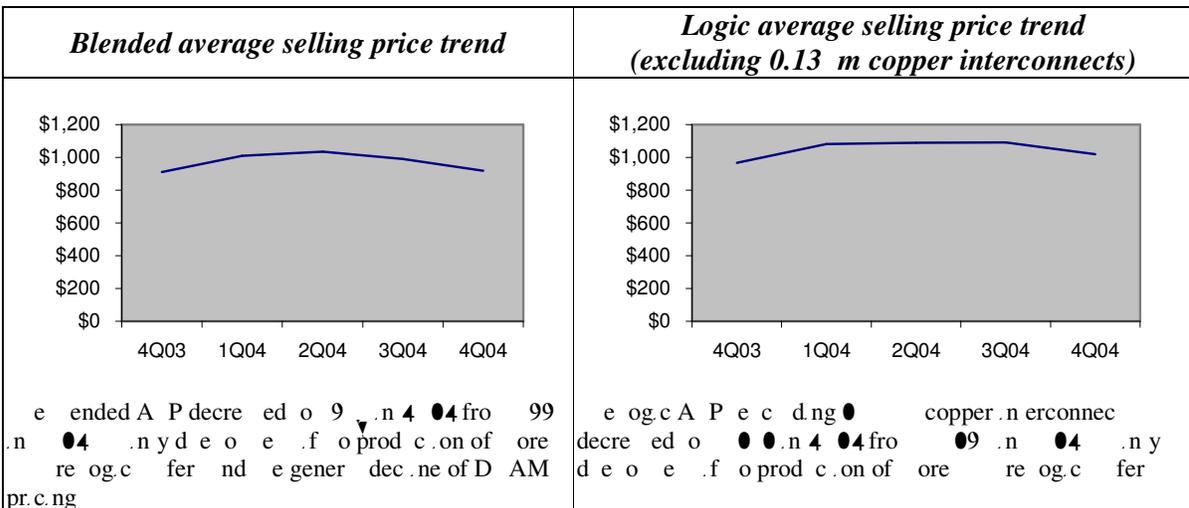
- At the end of 4Q04, capacity increased to 4.4 million wafers per month.

**Shipment and utilization:**

8" wafers	4Q04	3Q04	2Q04	1Q04	4Q03
Shipment	0.9	0.4	0.4	0.4	0.4
Capacity utilization <sup>(1)</sup>	99	99	99	99	99

Note:  
(1) Capacity utilization based on total wafer out divided by estimated capacity

- Shipment increased to 0.9 million wafers per month in 4Q04 from 0.4 million wafers per month in 3Q04 and 0.4 million wafers per month in 2Q04.
- Capacity utilization decreased to 99% in 4Q04.





## 2. Detailed financial analysis

### Gross profit analysis

Amounts in \$ thousands	4Q04	3Q04	QoQ	4Q03	YoY
Cost of sales	0	0	0	4	0
Depreciation	0	0	0	9	0
Other non-financing costs	0	94	0	0	0
Gross profit	9	0	0	0	9
Gross margin	0	4	0	0	0

- Cost of sales increased 0% in 4Q04 from 0% in 3Q04 primarily due to the increase in ferrous pig iron and increased depreciation expense in connection with the revaluation of depreciation expense.
- Gross profit decreased 9% in 4Q04 down from 0% in 3Q04 and 9% from 0% in 4Q03.
- Gross margin decreased 0% in 4Q04 from 4% in 3Q04 primarily due to the increase in depreciation and other non-financing costs of 94,000 in 4Q04 compared to 0 in 3Q04 and 0 in 4Q03.

### Operating expense analysis

Amounts in \$ thousands	4Q04	3Q04	QoQ	4Q03	YoY
Cost of operations	0	99	0	0	0
Research and development	40	0	0	94	94
General and administrative	44	99	49	9	0
Logistics	0	0	0	0	0
Amortization of deferred acquisition costs	9	4	0	0	0

- Cost of operations increased 0% in 4Q04 primarily due to 0% in 3Q04 and 0% in 4Q03.
- Research and development expense increased 40% in 4Q04 primarily due to 0% in 3Q04 and 94% in 4Q03. Being recognized in depreciation expense.
- General and administrative expense increased 44% in 4Q04 from 0% in 3Q04 primarily due to 99% in 4Q03 and 9% in 4Q03.
- Logistics expense increased 0% in 4Q04 primarily due to 0% in 3Q04 and 0% in 4Q03.
- Amortization of deferred acquisition costs increased 9% in 4Q04 primarily due to 4% in 3Q04 and 0% in 4Q03.



- Other non operating income of 4 million in 4Q04 decreased primarily due to foreign exchange gain of 1 million on revaluation of non operating currency receivables from financial instruments in connection with the revaluation of the deferred other income expense.

### 3. Liquidity

Amounts in \$ thousands	4Q04	3Q04
Change in cash and cash equivalents	0	9
Operating activities	0	9
Accounts receivable	9	
Inventory	44	4
Other	4	
Prepaid expenses	9	9
Accounts payable	4	4
Change in portion of long term debt	9	9
Other	4	4
Prepaid expenses	0	994
Change in cash	0	0
Change in cash		
Change in cash		4

- Change in cash and cash equivalents decreased to 0 million from 9 million primarily due to operating activities.

### Receivable/Inventory days outstanding trends





## Capital Structure

Amounts in \$ thousands	4Q04	3Q04
Current liabilities	0	9
Other liabilities	0	9
Other borrowings	9	0
Current portion of long-term debt	9	9
Long-term debt	44	44
Other debt	4	4
Net debt	99	4
Other equity	94	9
Other equity		4

- Other debt increased 4 million from 4 million to 4 million.
- Other debt increased 4 million from 4 million to 4 million.

## 4. Cashflow & Capex

Amounts in \$ thousands	4Q04	3Q04
Net cash provided by operating activities		9
Depreciation and amortization	4	
Provision for doubtful accounts	4	
Amortization of acquired intangible assets	4	
Net cash generated	4	4

## Capex plans

- Capex spend for 2004 is expected to be 4 million.
- Planned capex spend for 2005 is expected to be 2 million.

## 5. 1Q05 guidance

- Operating expenses are expected to decrease by 0%.
- Amortization is expected to decrease by 0%.
- Bad debt expense is expected to decrease by 0%.
- Provision for doubtful accounts is expected to decrease by 0%.
- Operating expenses as a percentage of revenue are expected to be 4%.
- Capex spend is expected to be 0 million.
- Depreciation and amortization is expected to be 0 million.
- Deferred stock compensation charge is expected to be 4 million.

## 6. Recent announcements

- MCA completed the acquisition of Manganese Corporation.
- MCA and Core Sign Cooperation Agreement.
- MCA received EMCONC.
- MCA completed the offering for B-ping.



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*Please visit SMIC's website <http://www.smics.com> for further details regarding the above announcements.*

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**Semiconductor Manufacturing International Corporation**  
**CONSOLIDATED BALANCE SHEET**  
(In US dollars)

	As of the end of	
	December 31, 2004 (audited)	September 30, 2004 (unaudited)
<b>ASSETS</b>		
Current assets:		
Cash and cash equivalents	607,172,570	950,164,909
Accounts receivable, net of allowances of \$1,105,165 and \$1,211,681	20,364,000	20,823,320
Prepaid expenses and other current assets	1,947,700	12,842,994
Assets held for sale	34,875,320	1,831,972
<b>Total current assets</b>	<b>664,357,790</b>	<b>985,663,295</b>
Land use rights, net	34,830,167	38,187,774
Plant and equipment	1,705,221,405	1,609,340,793
Accumulated depreciation	(162,127,180)	(170,210,199)
<b>Total non-current assets</b>	<b>1,577,924,692</b>	<b>1,477,368,368</b>
<b>Total assets</b>	<b>2,242,282,482</b>	<b>2,463,031,663</b>
Current liabilities:		
Accounts payable	191,986,372	191,983,707
Current portion of long-term debt	152,000	-
Income tax payable	730,320,536	604,084,156
<b>Total current liabilities</b>	<b>1,074,306,908</b>	<b>796,067,863</b>
<b>Total liabilities</b>	<b>1,074,306,908</b>	<b>796,067,863</b>
<b>Total equity</b>	<b>1,167,975,574</b>	<b>1,666,963,800</b>



**Semiconductor Manufacturing International Corporation**  
**CONSOLIDATED STATEMENT OF OPERATIONS**  
(In US dollars)

	For the three months ended	
	December 31, 2004 (unaudited)	September 30, 2004 (unaudited)
225 Sales	291,841,924	274,897,000
928 Cost of sales	229,573,732	199,163,000
528 Cost of sales - Amortization of deferred stock compensation	3,151,575	3,223,000
<b>9,769 Gross Profit</b>	<b>59,116,617</b>	<b>72,508,000</b>
<b>Operating expenses</b>		
20,688,265 Research and development	27,406,568	27,406,568
3,831,441 General and administrative	25,476,267	25,476,267
1,899,002 Selling and marketing	2,543,654	2,543,654
- Litigation settlement	23,153,105	23,153,105
2,442,449 Amortization of deferred stock compensation	3,025,196	3,025,196
<b>29,860,157 Total operating expense</b>	<b>82,504,780</b>	<b>82,504,780</b>
<b>Income from operations</b>	<b>(23,388,163)</b>	<b>(10,000,000)</b>
<b>Other income (expenses)</b>		
63,727 Interest income	3,107,173	3,107,173
80,725 Interest expense	(3,614,187)	(3,614,187)
75,193 Others, net	(2,687,195)	(2,687,195)
<b>8,200 Total other income (expenses), net</b>	<b>(3,194,209)</b>	<b>(3,194,209)</b>
<b>Net income (loss) before income tax</b>	<b>(31,582,372)</b>	<b>(13,194,209)</b>
<b>Income tax expense</b>		
1,175,503	1,346,112	1,346,112
2,289,305	1,667,791	1,667,791
460,378	539,681	539,681
<b>4,925,186 Total income tax expense</b>	<b>3,553,584</b>	<b>3,553,584</b>
<b>Net income (loss)</b>	<b>(36,507,558)</b>	<b>(16,747,793)</b>



**Semiconductor Manufacturing International Corporation**  
**CONSOLIDATED STATEMENT OF CASH FLOWS**  
(In US dollars)

	For the three months ended	
	December 31, 2004 (unaudited)	September 30, 2004 (unaudited)
<b>Operating activities:</b>		
Income (loss) attributable to holders of ordinary shares	(11,216,007)	39,343,294
Deemed dividends on preference shares	-	-
Net income	(11,216,007)	39,343,294
Adjustments to reconcile net income to net cash provided by (used in) operating activities:		
231 Gain (loss) on disposal of plant and equipment	(69,916)	(486)
855 Bad debt expense	683,484	64
39,970 Depreciation and amortization	148,271,100	127,225,000
Amortization of intangible assets	-	4,091,723
Amortization of deferred stock compensation	-	7,076,366
Changes in operating assets and liabilities:		
(55,592,431) Accounts receivable		17,363,354
(21,194,466) Inventories		(9,260,846)
115,508 Prepaid expense and other current assets		(5,852,079)
8,805,298 Accounts payable		5,603,223
Other operating assets and liabilities		(1,120,000)
Net cash provided by operating activities	130,299,498	174,237,329
Investing activities:		
Capital expenditures	(1,120,000)	(1,120,000)
Acquisition of intangible assets	(4,091,723)	(4,091,723)
Acquisition of other operating assets	(1,120,000)	(1,120,000)
Net cash used in investing activities	(6,331,723)	(6,331,723)
Financing activities:		
Proceeds from the issuance of ordinary shares	1,120,000	1,120,000
Proceeds from the issuance of preference shares	1,120,000	1,120,000
Proceeds from bank borrowings	1,120,000	1,120,000
Proceeds from other financing activities	1,120,000	1,120,000
Net cash provided by financing activities	4,500,000	4,500,000
Net change in cash and cash equivalents	128,467,775	168,405,606
Cash and cash equivalents at the beginning of the period	1,120,000	1,120,000
Cash and cash equivalents at the end of the period	129,587,775	169,525,606